



Please amend the application as follows:

In the Claims:

Please cancel non-elected Claims 22-28 without prejudice.

Please add the following new claims:

29. (new) A packaged integrated circuit, comprising:

A¹
a substrate including an insulating material and a conductive material disposed over the insulating material, the conductive material comprising a plurality of contacts, the conductive material further comprising a conductive ring disposed around the periphery of said plurality of contacts.

30. (new) The packaged integrated circuit of Claim 29, wherein said conductive material further comprises a trace formed of said conductive material over said insulating material and connected to said conductive ring such that said trace surrounds a selected one of said plurality of contacts.

31. (new) The packaged integrated circuit of Claim 29, wherein said conductive material further comprises a trace formed of said conductive material over said insulating material and connected to said conductive ring such that said trace surrounds selected contacts in said plurality of contacts.

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.